

AMENDMENT TO THE SPECIFICATION

Please amend the specification by substituting the following paragraph [0013] for the corresponding paragraph currently in the application.

[0013] A power chip 16 is shown in Figure 1 as being mounted to a surface of the ceramic substrate 12. The chip 16 is depicted as a semiconductor die having a frontside (lower surface in Figure 1) and an oppositely-disposed topside (upper surface in Figure 1). The power chip 16 is mounted to the ceramic substrate 12 by reflow-soldering one or more bond pads or other suitable terminals (not shown) on the frontside of the power chip 16 to one or more conductors 18 on the surface of the ceramic substrate 12 to yield solder connections 20. The power chip 16 may also have circuit elements, e.g., integrated circuitry, conductive traces, bond pads, etc. (not shown) on its topside which also require electrical connections. For this purpose, the chip 16 is shown in Figure 1 as being coupled to a heat-conductive structure 22 disclosed in commonly-assigned U.S. Patent Application Serial No. 10/385,106, now U.S. Patent No. 6,873,043 {~~Attorney Docket No. DP-308378~~} to Oman. The heat-conductive structure 22 enables and promotes the conduction of heat to the ceramic substrate 12, as well as to a heat sink pedestal 24 described in fuller detail below.